

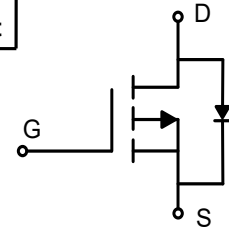
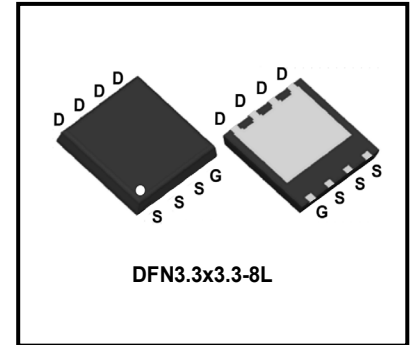
40V P-Channel Enhancement Mode Power MOSFET

Description

WMQ50P04TS uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Features

- $V_{DS} = -40V$, $I_D = -50A$
 $R_{DS(on)} < 8.5m\Omega @ V_{GS} = -10V$
 $R_{DS(on)} < 11m\Omega @ V_{GS} = -4.5V$
- Green Device Available
- Low Gate Charge
- 100% EAS Guaranteed



Applications

- Power Management Switches
- DC/DC Converter

Absolute Maximum Ratings (T_A = 25°C, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-40	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	T _C =25°C	-50
		T _C =100°C	-32
Pulsed Drain Current ¹	I_{DM}	-200	A
Single Pulse Avalanche Energy ²	EAS	125	mJ
Total Power Dissipation	P_D	35.7	W
Operating Junction and Storage Temperature Range	T_J , T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	R_{θJA}	56	°C/W
Thermal Resistance from Junction-to-Case	R_{θJC}	3.5	°C/W

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-40	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA
Zero Gate Voltage Drain Current	$T_J=25^\circ\text{C}$	$V_{DS} = -40V, V_{GS} = 0V$	-	-	-1	μA
	$T_J=100^\circ\text{C}$		-	-	-100	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-1.6	-2.5	V
Drain-Source on-Resistance ⁴	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -20A$	-	6.8	8.5	m Ω
		$V_{GS} = -4.5V, I_D = -15A$	-	8.5	11	
Forward Transconductance ⁴	g_{fs}	$V_{DS} = -10V, I_D = -20A$	-	104	-	S
Dynamic Characteristics⁵						
Input Capacitance	C_{iss}	$V_{DS} = -20V, V_{GS} = 0V, f = 1MHz$	-	5295	-	μF
Output Capacitance	C_{oss}		-	430	-	
Reverse Transfer Capacitance	C_{rss}		-	385	-	
Gate Resistance	R_g	$f = 1MHz$	-	4.1	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q_g	$V_{GS} = -10V, V_{DS} = -20V, I_D = -20A$	-	110	-	nC
Gate-Source Charge	Q_{gs}		-	12.5	-	
Gate-Drain Charge	Q_{gd}		-	23	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = -10V, V_{DD} = -20V, R_G = 3\Omega, I_D = -20A$	-	16.8	-	ns
Rise Time	t_r		-	10	-	
Turn-off Delay Time	$t_{d(off)}$		-	65	-	
Fall Time	t_f		-	17	-	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -20A, di/dt = -100A/\mu s$	-	42	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	29	-	nC
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$I_S = -20A, V_{GS} = 0V$	-	-	-1.2	V
Continuous Source Current	$T_C=25^\circ\text{C}$	I_S	-	-	-50	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$.
2. The EAS data shows Max. rating . The test condition is $V_{DD} = -25V, V_{GS} = -10V, L = 0.4mH, I_{AS} = -50A$.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

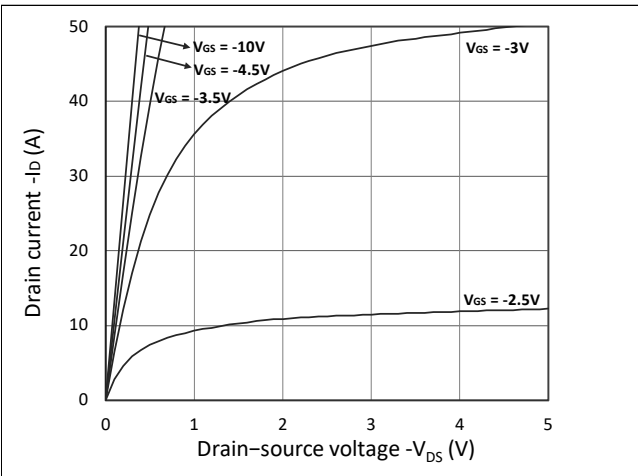


Figure 1. Output Characteristics

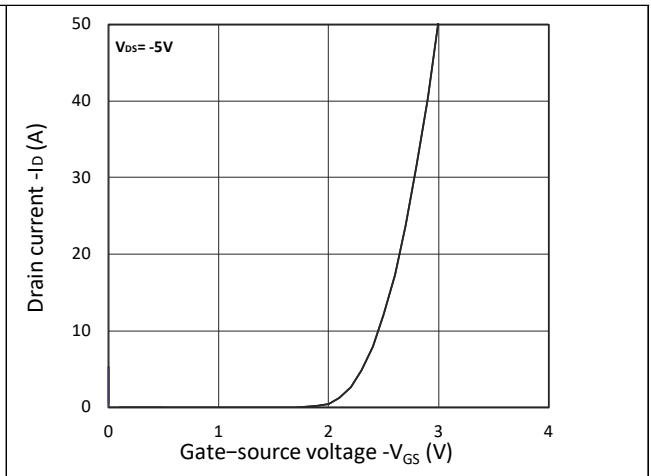


Figure 2. Transfer Characteristics

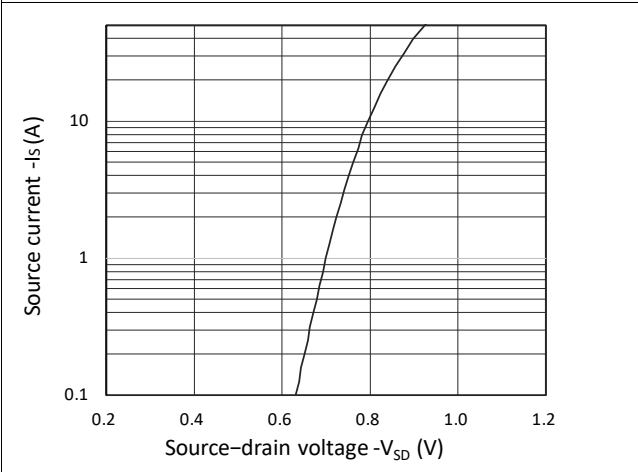


Figure 3. Forward Characteristics of Reverse

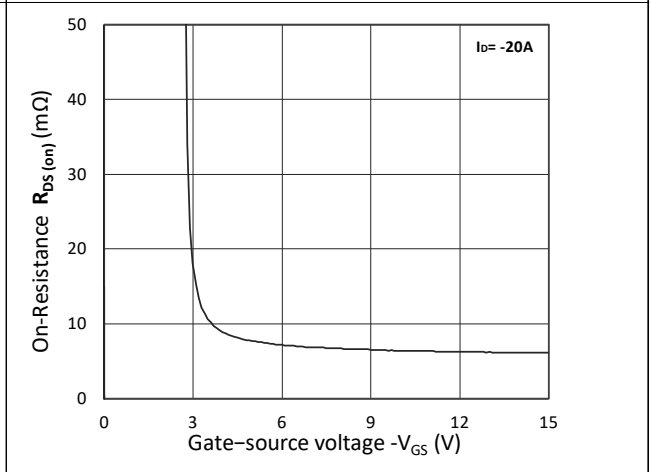


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

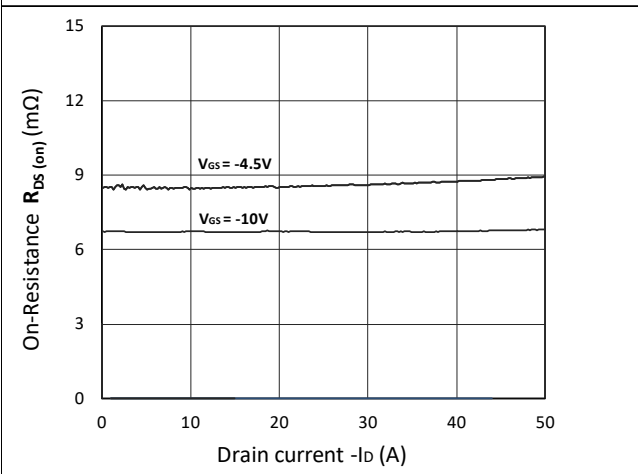


Figure 5. $R_{DS(ON)}$ vs. I_D

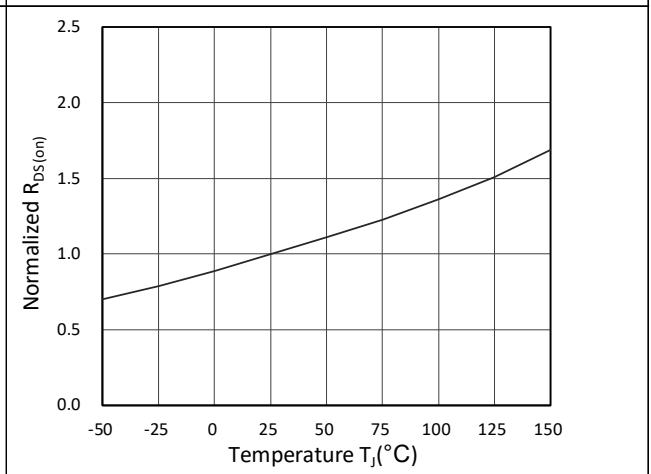


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

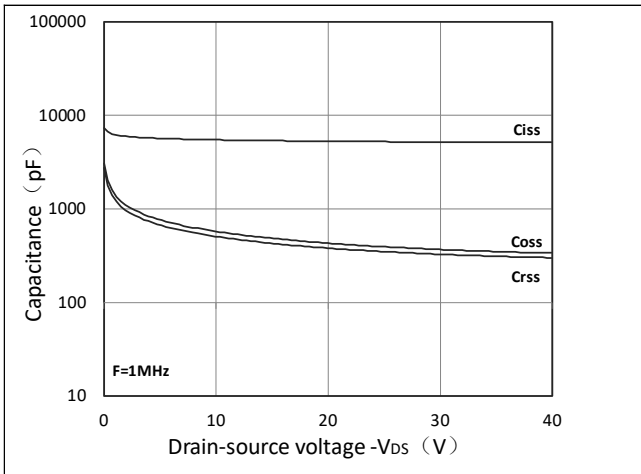


Figure 7. Capacitance Characteristics

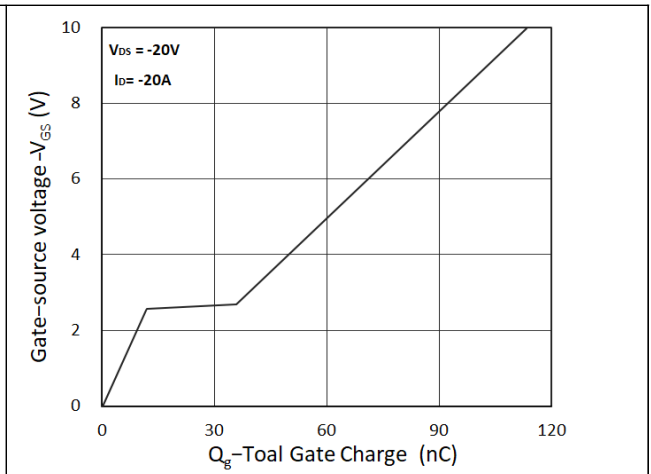


Figure 8. Gate Charge Characteristics

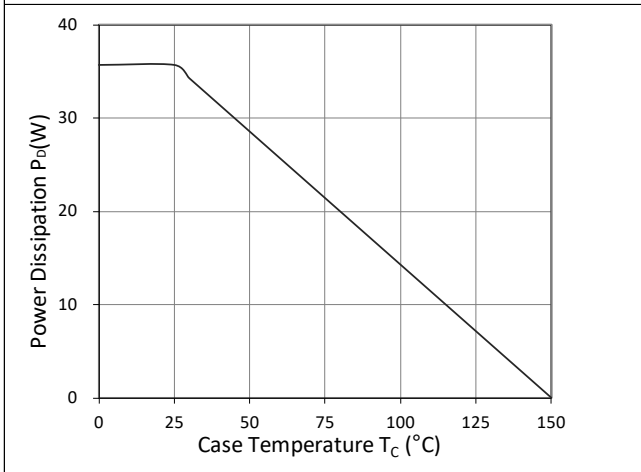


Figure 9. Power Dissipation

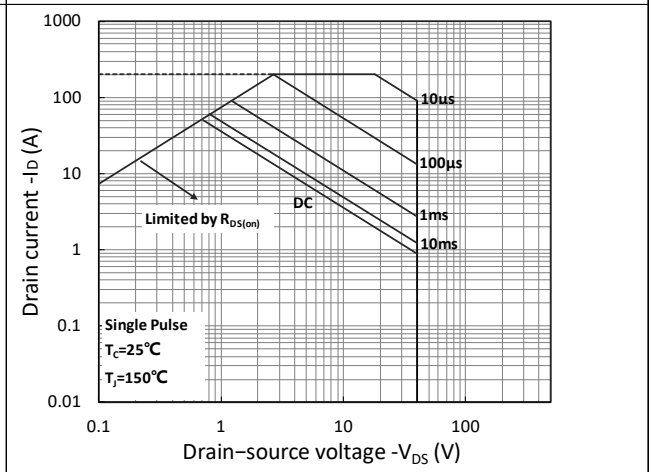


Figure 10. Safe Operating Area

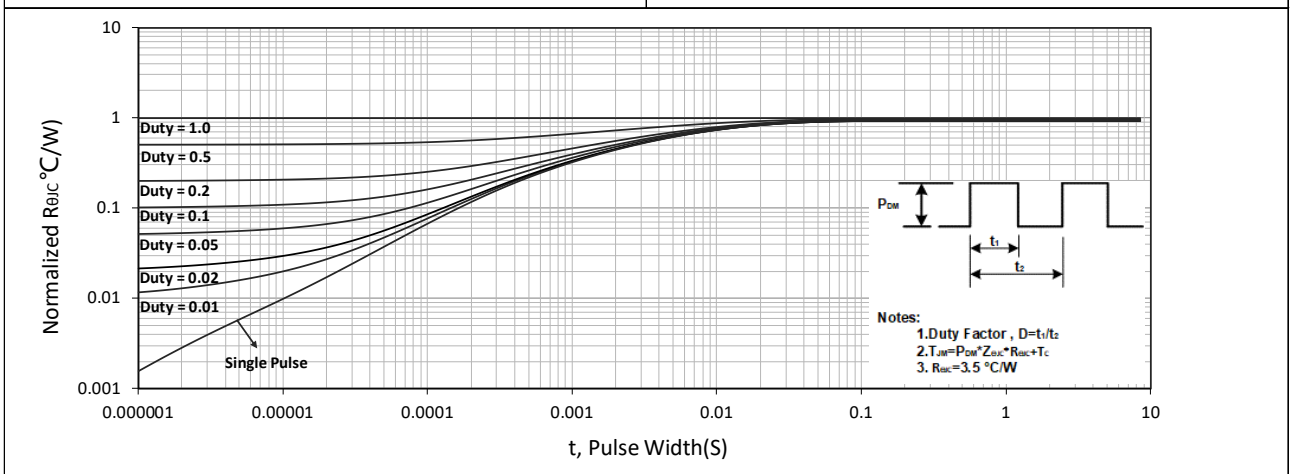


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

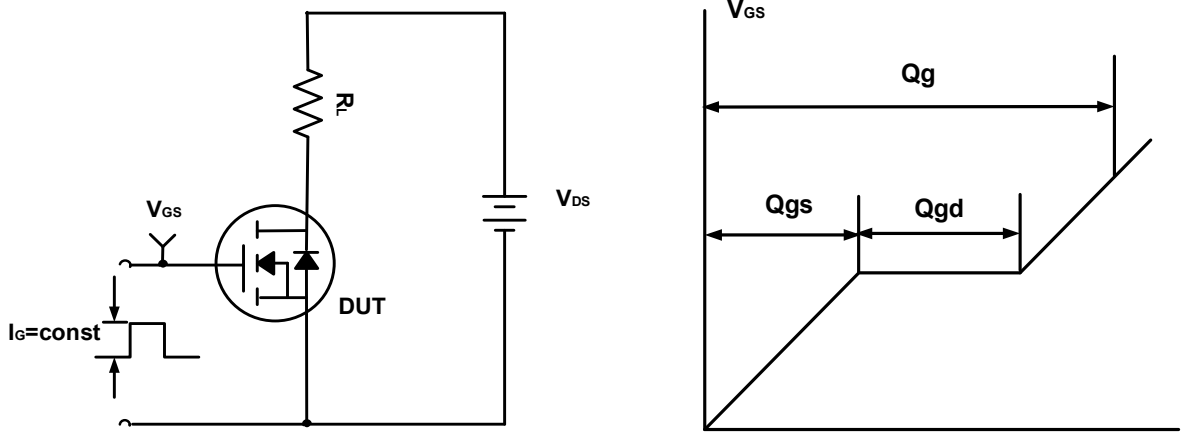


Figure A. Gate Charge Test Circuit & Waveforms

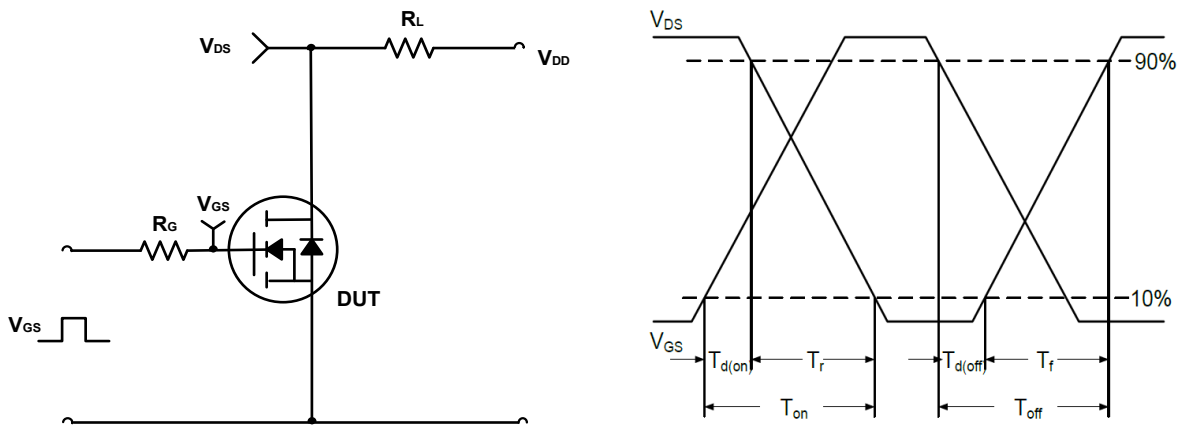


Figure B. Switching Test Circuit & Waveforms

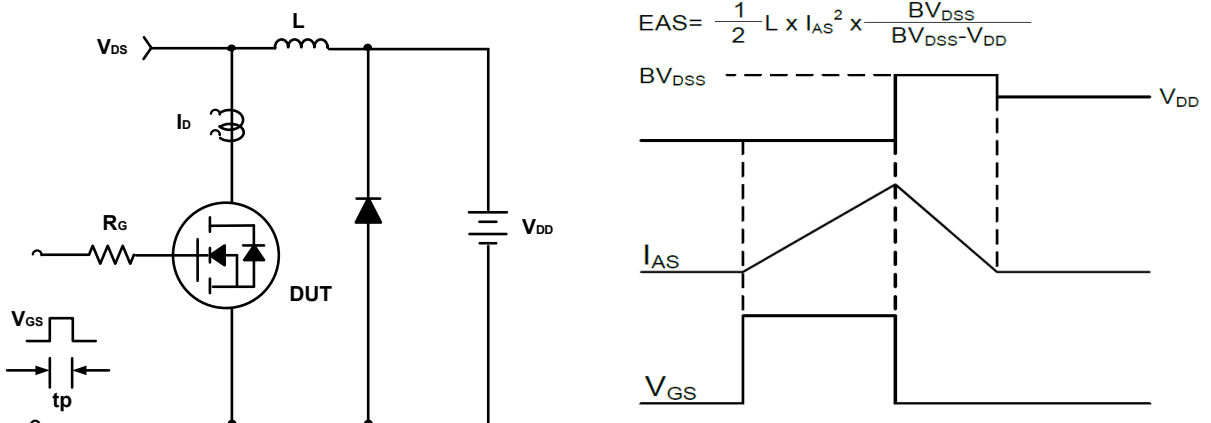
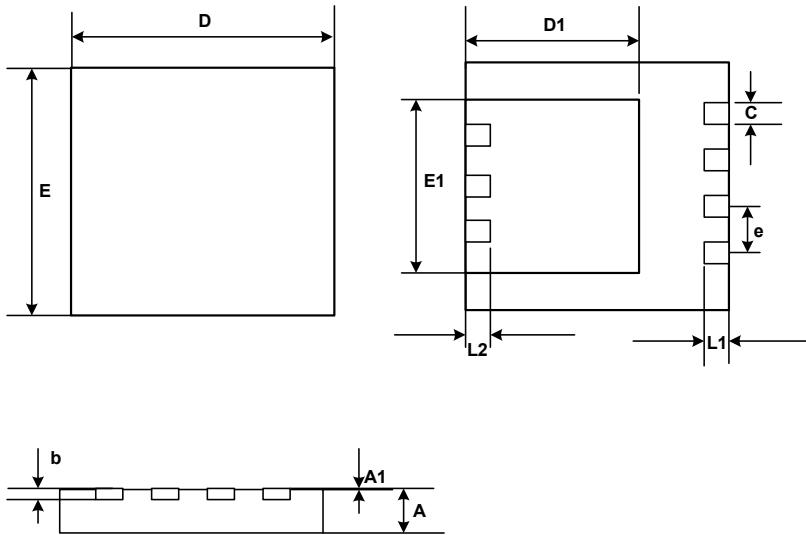


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Mechanical Dimensions for DFN3.3x3.3-8L

COMMON DIMENSIONS



SYMBOL	MM	
	MIN	MAX
A	0.700	0.800
A1	0.000	0.050
b	0.216 REF	
c	0.290	0.390
e	0.65BSC	
D	3.200	3.400
D1	2.020	2.220
E	3.200	3.400
E1	2.190	2.390
F	0.405	0.605
L1	0.350	0.550
L2	0.300	0.500

Ordering Information

Part	Package	Marking	Packing method
WMQ50P04TS	DFN3.3x3.3-8L	Q50P04S	Tape and Reel

Marking Information

Q50P04S = Device code

WWXXXXX= Date code

Contact Information

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